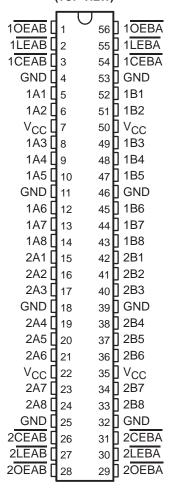
- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Lavout
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OI})
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'ABT16543 16-bit registered transceivers contain two sets of D-type latches for temporary storage of data flowing in either direction. The 'ABT16543 can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable (\overline{CEAB}) input must be \underline{low} to enter data from A or to output data from B. If \overline{CEAB} is low and \overline{LEAB} is low, the A-to-B latches are transparent; a subsequent low-to-high transition of \overline{LEAB} puts the A latches in the storage mode. With \overline{CEAB} and \overline{OEAB} both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the \overline{CEBA} , \overline{LEBA} , and \overline{OEBA} inputs.

SN54ABT16543 . . . WD PACKAGE SN74ABT16543 . . . DGG OR DL PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16543 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16543 is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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SN54ABT16543, SN74ABT16543 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS087C - FEBRUARY 1991 - REVISED JANUARY 1997

FUNCTION TABLE† (each 8-bit section)

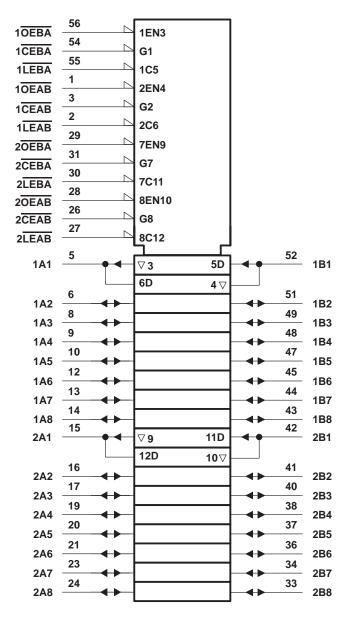
	INPL	JTS		OUTPUT
CEAB	LEAB	OEAB	В	
Н	Х	Х	Χ	Z
Х	Χ	Н	Χ	Z
L	Н	L	Χ	в ₀ ‡
L	L	L	L	L
L	L	L	Н	Н

[†] A-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.



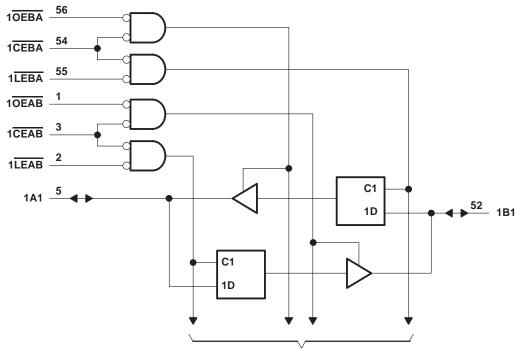
[‡] Output level before the indicated steady-state input conditions were established

logic symbol†

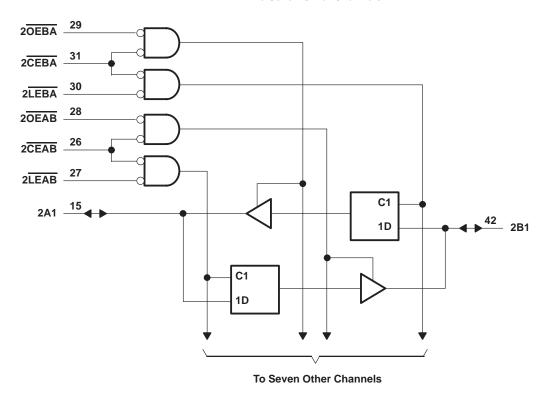


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Seven Other Channels





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V _O	–0.5 V to 5.5 V
Current into any output in the low state, I _O : SN54ABT16543	96 mA
SN74ABT16543	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN54ABT	16543	SN74AB1	16543	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage		0.8		0.8	V	
٧ _I	Input voltage		0	Vcc	0	VCC	V
loh	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature	•	– 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

SN54ABT16543, SN74ABT16543 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS087C - FEBRUARY 1991 - REVISED JANUARY 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAE	DAMETED	TEST COL	UDITIONS	Т	A = 25°C	;	SN54AB	Γ16543	SN74AB1	Γ16543	UNIT
PAR	RAMETER	TEST CO	NULLIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNII
٧ıĸ		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
V		V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				V
		VCC = 4.5 V	I _{OH} = -32 mA	2*					2		
V/		V 45V	I _{OL} = 48 mA			0.55		0.55			V
VOL		V _{CC} = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V
V _{hys}					100						mV
l _l	Control inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		±1		±1	μΑ
-	A or B ports	1				±100		±100		±100	
lozh‡		V _{CC} = 5.5 V,	V _O = 2.7 V			50**		10		50	μΑ
lozL [‡]		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			-50**		-10		-50	μΑ
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
I _{CEX}		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ
ΙΟ [§]		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-200	-50	-200	-50	-200	mA
		V _{CC} = 5.5 V,	Outputs high			2		2		2	
ICC	A or B ports	$I_{O} = 0$,	Outputs low			35		35		35	mA
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2	
ΔICC¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				0.5		0.5		0.5	mA
Ci	Control inputs	V _I = 2.5 V or 0.5 V	V _I = 2.5 V or 0.5 V		3						pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			8.5						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V _{CC} =	= 5 V, 25°C	SN54AB1	Г16543	SN74AB1	16543	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX		
t _W	Pulse duration, LEAB or LEBA low		4		4		4		ns
		High	1.5		1.5		1.5		no
t _{su}	Setup time, data before LEAB↑ or LEBA↑	Low	3.5		3.5		3.5		ns
4.	Hald Consider a form LEAD the same	High	1.5		1.5		1.5		ne
t _h	Hold time, data after LEAB↑ or LEBA↑	Low	2		2		2		ns



^{**} These limits apply only to the SN74ABT16543.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters IOZH and IOZL include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $[\]P$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V $_{CC}$ or GND.

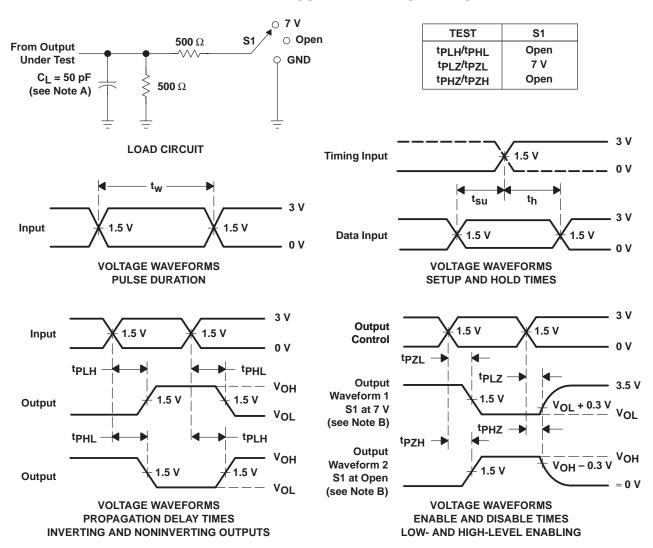
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

				SN5	4ABT16	543		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V A = 25°C	<i>'</i> ,	MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	0.8	2.5	3.3	0.8	3.9	ns
^t PHL	AOIB	BULK	0.9	2.7	4.4	0.9	5.2	115
t _{PLH}	Œ	A or B	1	3.1	4.3	1	5.3	ns
^t PHL	LE	AOIB	1.2	3.3	4.8	1.2	5.7	113
^t PZH	ŌĒ	A or B	0.8	3.4	4.3	0.8	5.3	H ns ∣
tPZL	OE	AOID	1.1	3.8	7	1.1	7.9	
t _{PHZ}	ŌĒ	A or B	1.9	4	6.3	1.9	7.2	ne
t _{PLZ}	OE	AOID	1.6	3.3	4.6	1.6	5	ns
^t PZH	CE	A or B	0.9	3.8	4.9	0.9	6.3	20
t _{PZL}	CE	AUID	1.2	4.2	6.8	1.2	7.9	ns
^t PHZ	CE	A or B	2	4.5	6.4	2	7.3	nc
t _{PLZ}	CE	AUID	1.7	3.9	5.1	1.7	5.6	ns I

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

				SN7	4ABT16	543		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V A = 25°C	<i>'</i> ,	MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	1	2.5	3.3	1	3.8	ns
^t PHL	AUD	BOIA	1	2.7	4.4	1	5.1	113
t _{PLH}	Œ	A or B	1	3.1	4.3	1	5.2	ns
t _{PHL}	LE	AOID	1.2	3.3	4.8	1.2	5.6	113
^t PZH	ŌĒ	A or B	1	3.4	4.3	1	5.2	—l ns
tPZL	OE .	AOID	1.1	3.8	5.9	1.1	7	
^t PHZ	ŌĒ	A or B	1.9	4	5	1.9	5.7	ne
tPLZ	OE .	AOID	1.6	3.3	4.2	1.6	4.6	ns
^t PZH	CE	A or B	1	3.8	4.9	1	6.2	ne
t _{PZL}	CE	AUID	1.2	4.2	6.5	1.2	7.8	ns
^t PHZ	CE	A or B	2	4.5	5.6	2	6.6	ne
t _{PLZ}	CE	AUID	1.7	3.9	5.1	1.7	5.4	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Q} = 50 Ω , t_{f} \leq 2.5 ns, t_{f} \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGE OPTION ADDENDUM



4-Feb-2021

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9324101MXA	ACTIVE	CFP	WD	56	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9324101MX A SNJ54ABT16543W D	Samples
74ABT16543DGGRG4	ACTIVE	TSSOP	DGG	56	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16543	Samples
SN74ABT16543DGGR	ACTIVE	TSSOP	DGG	56	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16543	Samples
SN74ABT16543DL	ACTIVE	SSOP	DL	56	20	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16543	Samples
SN74ABT16543DLR	ACTIVE	SSOP	DL	56	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16543	Samples
SNJ54ABT16543WD	ACTIVE	CFP	WD	56	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9324101MX A SNJ54ABT16543W D	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

PACKAGE OPTION ADDENDUM



4-Feb-2021

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ABT16543, SN74ABT16543:

Catalog: SN74ABT16543

Military: SN54ABT16543

NOTE: Qualified Version Definitions:

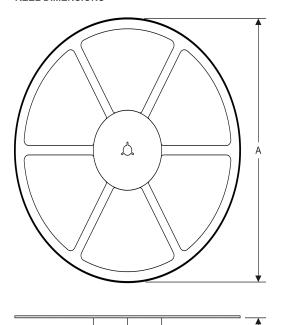
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

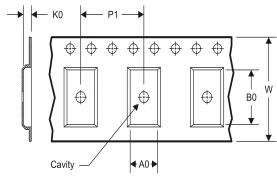
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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

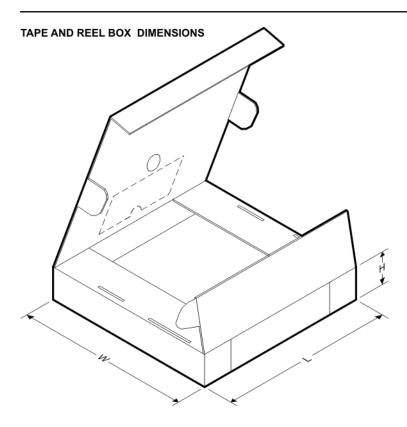
*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16543DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ABT16543DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1



PACKAGE MATERIALS INFORMATION

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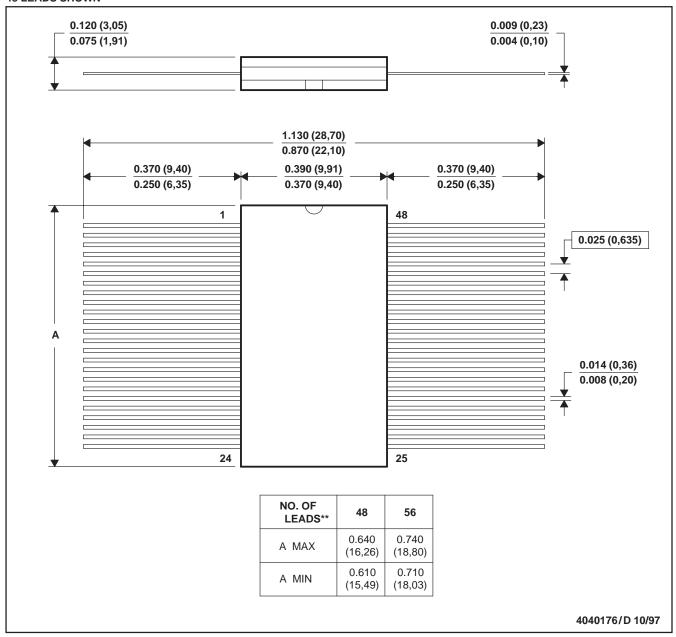
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16543DGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0
SN74ABT16543DLR	SSOP	DL	56	1000	367.0	367.0	55.0

WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



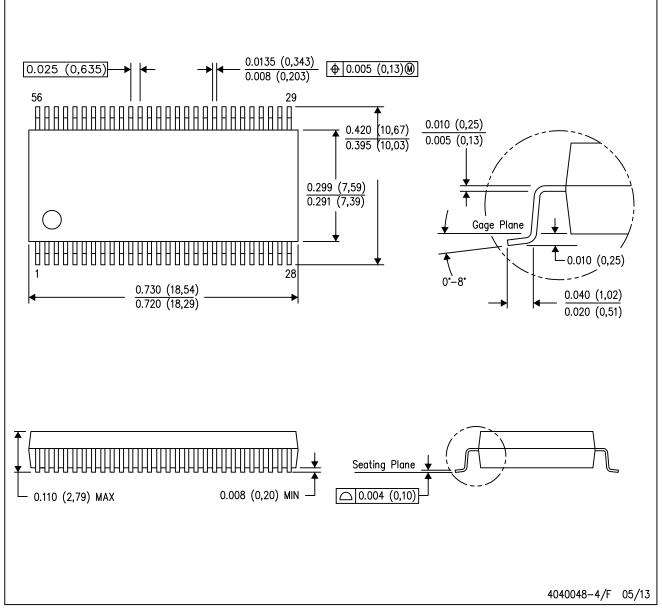
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA GDFP1-F56 and JEDEC MO-146AB



DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

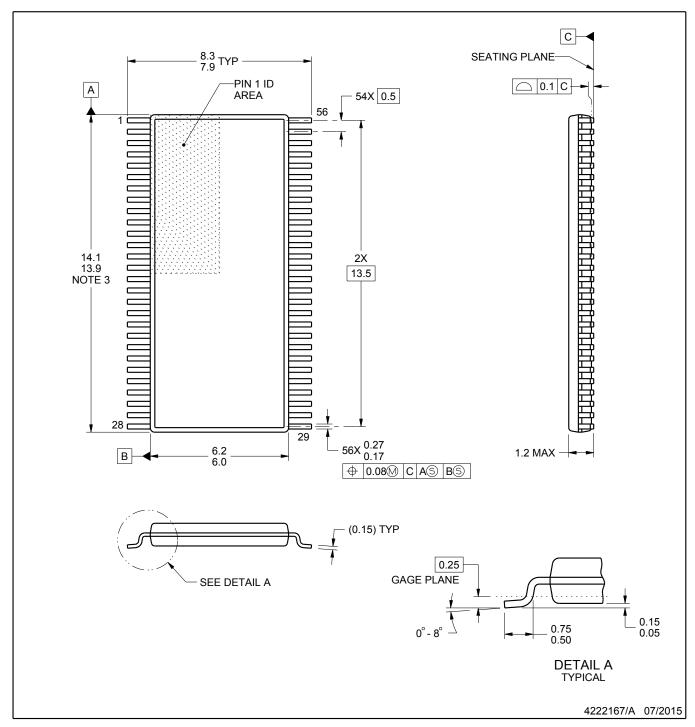
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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SMALL OUTLINE PACKAGE



NOTES:

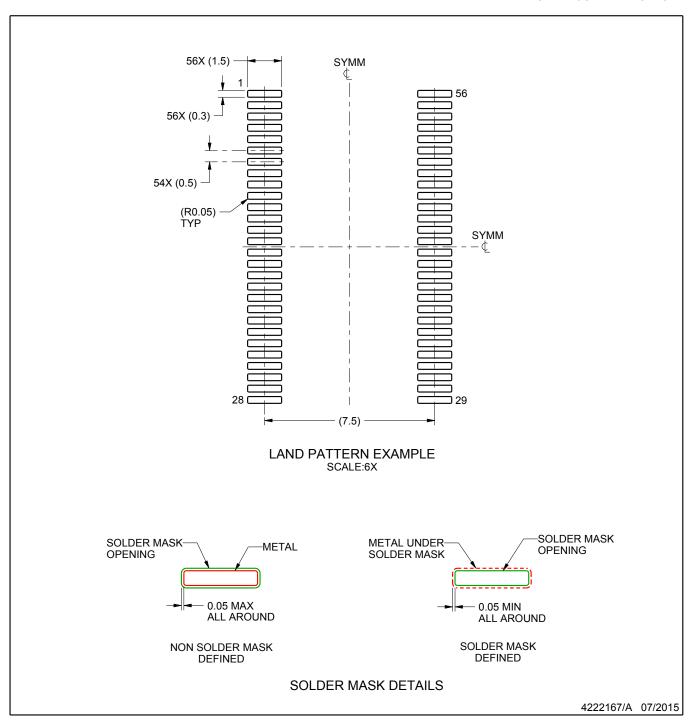
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



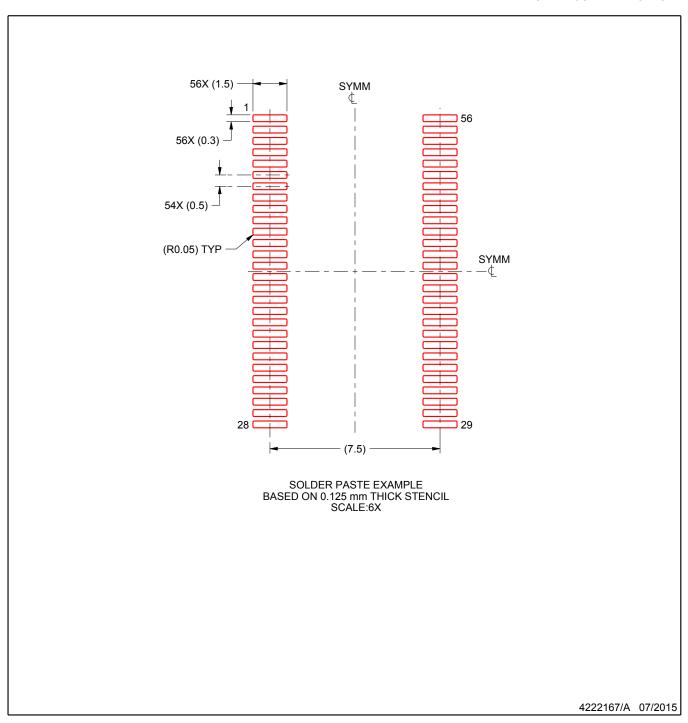
SMALL OUTLINE PACKAGE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

SMALL OUTLINE PACKAGE



NOTES: (continued)

- Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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